

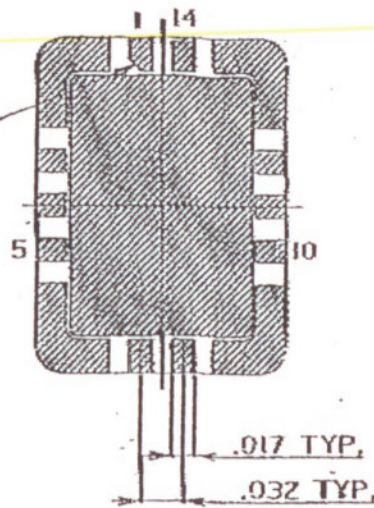
- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED
 3. DIE ATTACH AREA TO BE METALLIZED
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

FW0141370-10-0

CHANGE	DATE	DRAWN	CHECKED	APPROVED	NAME	14 LEAD FLAT PACKAGE	TOLERANCES	± .005	DRAWN	CHECKED
					SCALE	5 : 1	MATERIAL	AS INDICATED	APPROVED	DATE
					KYOCERA CORPORATION		KYOTO JAPAN	DWG. NO.	KD-F87370	
									MAY.08.'87	

CCF01439

.010 x 45° CHAMFER
PIN NO. 1 INDEX



BONDING PATTERN

					NAME	14 LEAD FLAT PACKAGE	TOLERANCES:	DRAWN	CHECKED
					SCALE	MATERIAL	UNLESS OTHERWISE SPECIFIED	<i>A. Satoyama</i>	<i>K. Aoki</i>
					10 : 1			APPROVED	DATE
								<i>K. Aoki</i>	MAY.03.87
					KYOCERA CORPORATION		KYOTO	DRWG. NO. KD-F87370	